Materials Declaration

Package	PBGA
Body Size	27 X 27
Ball Count	400
Option	SnPbAg
Ball Size	0.76 mm

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	13.7	1.50 E-01	48319
SiO2 Filler	85	9.28 E-01	299787
Sb2O3	1	1.09 E-02	3527
Carbon Black	0.3	3.28 E-03	1058

Molding Compound

Item	PPM	Method
Pb	<10	ICP-AES
Cd	<5	ICP-AES
Hg	<10	ICP-AES
Cr+6	<10	ICP-AES

Laminate

Item	% of Laminate	Weight (g)	PPM
BT Epoxy Resin	46	5.03 E-01	162372
Copper (Cu)	33.406	3.68 E-01	119006
Main agent	7.11	7.84 E-02	25329
Hardener	3.049	3.36 E-02	10862
Copper (Cu)	0.672	7.41 E-03	2394
Nickel (Ni)	7.445	8.21 E-02	26522
Gold (Au)	1.742	1.92 E-02	6206

Solder Ball

	% of Solder Ball	Weight (g)	PPM
Sn	62	4.86 E-01	157032
Pb	36	2.82 E-01	91180
Ag	2	1.57 E-02	5066

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.70 E-02	5491

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.01 E-01	32621

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	80	8.00 E-03	2584
Resin	20	2.00 E-03	646

Package Totals

Weight (g)	PPM
3.10 E+00	1000000

AST-B-E

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.